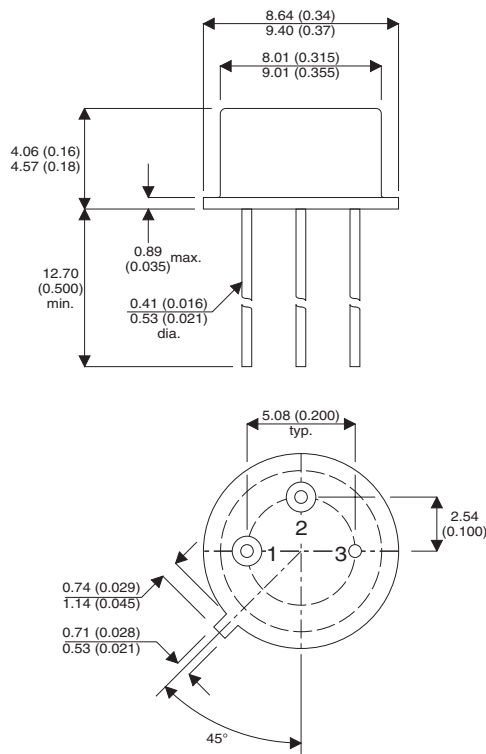


MECHANICAL DATA

Dimensions in mm (inches)



TO39 Package (TO-205AF)

Underside View

Pin 1 - Source

Pin 2 - Gate

Pin 3 - Drain and Case

N-CHANNEL POWER MOSFET ENHANCEMENT MODE

FEATURES

- REPETITIVE AVALANCHE RATING
- SIMPLE DRIVE REQUIREMENTS
- HERMETICALLY SEALED

APPLICATIONS

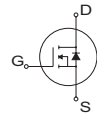
- FAST SWITCHING
- MOTOR CONTROLS
- POWER SUPPLIES

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$ unless otherwise stated)

V_{DS}	Drain Source Voltage	200V
$I_D @ T_{case} = 25^{\circ}C$	Continuous Drain Current	3.5A
$I_D @ T_{case} = 100^{\circ}C$	Continuous Drain Current	2.25A
I_{DM}	Pulsed Drain Current ¹	14A
V_{GS}	Gate Source Voltage	$\pm 20V$
$P_D @ T_{case} = 25^{\circ}C$	Maximum Power Dissipation	20W
$R_{\theta J-C}$	Thermal Resistance Junction To Case	6.25°C/W
$R_{\theta J-A}$	Thermal Resistance Junction To Ambient	175°C/W
T_J, T_{stg}	Operating and Storage Temperature Range	-55 to +150°C
Lead Temperature	(1.6mm from case for 10 secs)	300°C

Semelab Plc reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing orders.

ELECTRICAL CHARACTERISTICS ($T_{case} = 25^{\circ}C$ unless otherwise stated)

Parameter	Test Conditions	Min.	Typ.	Max.	Unit
STATIC ELECTRICAL RATINGS					
BV _{DSS} Drain – Source Breakdown Voltage	V _{GS} = 0 I _D = 1.0mA	200			V
V _{GS(th)*} Gate Threshold Voltage	V _{DS} = V _{GS} I _D = 250μA	2.0		4.0	
I _{GSSF} Gate Body Leakage Forward	V _{GS} = 20V			100	nA
I _{GSSR} Gate Body Leakage Reverse	V _{GS} = -20V			-100	
I _{DSS} Zero Gate Voltage Drain Current	V _{DS} = 160V. V _{GS} = 0			25	μA
	T _C = 125°C			250	
R _{DS(on)*} Static Drain Source On-State Resistance	V _{GS} = 10V I _D = 2.25A			0.80	Ω
	V _{GS} = 10V I _D = 3.5A			0.92	
gfs* Forward Transconductance	V _{DS} = 15V I _{DS} = 2.25A	1.5			S (ᵀ)
DYNAMIC CHARACTERISTICS					
C _{iss} Input Capacitance	V _{GS} = 0 V _{DS} = 25V f = 1.0MHz		260		pF
C _{oss} Output Capacitance			100		
C _{rss} Reverse Transfer Capacitance			30		
t _{d(on)} Turn–On Delay Time	V _{DD} = 100V I _D = 3.5A R _G = 7.5Ω (MOSFET switching times are essentially independent of operating temperature.)			40	ns
t _r Rise Time				50	
t _{d(off)} Turn–Off Delay Time				50	
t _f Fall Time				50	
Q _g Total Gate Charge	V _{GS} = 10V I _D = 3.5A V _{DS} = 100V	8.0		14.3	nC
Q _{gs} Gate To Source Charge		0.9		3.0	
Q _{gd} Gate To Drain (“Miller”) Charge		2.3		9.0	
BODY– DRAIN DIODE RATINGS & CHARACTERISTICS					
I _S Continuous Source Current (Body Diode)	Modified MOS POWER symbol showing the intergal  P-N junction rectifier.			3.5	A
I _{SM} Source Current (Body Diode)				14	
V _{SD} Diode Forward Voltage*	I _S = 3.5A V _{GS} = 0 T _J = 25°C			1.5	V
t _{rr} Reverse Recovery Time	I _F = 3.5A T _J = 25°C			400	ns
Q _{RR} Reverse Recovery Charge	d _i / d _t = 100A/μs V _{DD} = 50V			4.3	μC

Notes

* Pulse Test: Pulse Width $\leq 300\mu s$, $\delta \leq 2\%$